LEAD FRAMES, MICROELECTRONIC DEVICES WITH LEAD FRAMES, AND METHODS FOR MANUFACTURING LEAD FRAMES AND MICROELECTRONIC DEVICES WITH LEAD FRAMES

ABSTRACT OF THE DISCLOSURE

Lead frames, microelectronic devices with lead frames, and methods for manufacturing lead frames and microelectronic devices with lead frames are disclosed herein. An embodiment of one such microelectronic device includes a microelectronic die and a plurality of conductive leads connected to the die. The die includes an integrated circuit and a plurality of terminals operably coupled to the integrated circuit. The conductive leads are electrically coupled to corresponding terminals. The individual leads include a pad with a first side facing toward the die and a second side opposite the first side. The second side has a projection and/or a recess configured to interface with an interconnect element.

Figure.1